

附表 3-2:

批准证书附件

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No	Products, Materials	Items, Parameter		Title, Code of specification, standard or method used	Restriction or limitation	measuring capacity	Note
		No	Items, Parameter				
1	Electrical and electronic products/electronic semiconductor products	1	Steady-State Temperature-Humidity test	《Environmental testing of electrical and electronic products - Part 2: Test methods - Test Cab: Constant damp heat test》 GB/T 2423.3-2016	Test only: Temperature: +30℃ /+40℃, Relative humidity:85%RH/93%RH	Inner box size (L × W × H): 1000mm×1000mm ×1000mm	
				《Environmental testing of electrical and electronic products - Part 2: Test methods - Test Cy: Constant wet heat is mainly used for accelerated testing of components》 GB/T 2423.50-2012	Only: Temperature: +85℃, Relative humidity: 85%RH	Inner box size (L × W × H): 1000mm×1000mm ×1000mm	
		2	Temperature cycle test	《Environmental tests - Part 2: Test methods - Test N: temperature change》 GB/T 2423.22-2012	Test only: test Nb; Temperature: -65℃~ +150℃, Temperature change rate: ≤5℃ /min	Inner box size (L × W × H): 500mm×400mm× 400mm	
		3	Temperature storage test	《Environmental testing for electrical and electronic products - Part 2: Test methods - Test A: Low temperature》 GB/T 2423.1-2008	Test only: Method Ab; Temperature: -65℃~ +5℃	Inner box size (L × W × H): 1000mm×1000mm ×1000mm	
				《Environmental testing for electrical and electronic products - Part 2: Test methods - Test B: High temperature》 GB/T 2423.2-2008	Test only: Method Bb; Temperature: +30℃~ +250℃	Inner box size (L × W × H): 800mm×950mm× 1440mm	
		4	Visual inspection of appearance	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 2009.2	Measure only: magnification 3 times ~ 50 times		
5	Decap	Methods for destructive physical analysis of military electronic components GJB-4027B-2021 in 1103 in					

				2.6.2			
		6	Delayer	Test Methods and Procedures for Microelectronic Devices GJB-548C-2021 Method 5003 in 3.3.3		Sample size no exceed 8 inches	
		7	IV CURVE	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 5003 in 3.2.3.3.2.4		Range: $\pm 9v$ 500mA resolution 2uA	
		8	InGaAs/OBRICH	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 5003 in 3.4(d)		Wavelength: 1300nm, detection voltage range: 0~20v, detection current capacity: 0-100mA	
		9	PROBE	Test Methods and Procedures for Microelectronic Devices GJB-548C-2021 Method 5003 in 3.2.12			
		10	SAT	Physical Analysis Methods for Destructive Analysis of Military Electronic Components: GJB-4027B-2021, Method 1103, 2.5	Test only: 25MHZ PROBE FREQUENCY		
2	Nonhermetic Surface Mount Devices /Electronic Semiconductor Products	1	Pre-condition test	《Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing》 JSED22-A113I-2020 Clause5	Test only: Temperature storage: Temperature: 125℃ Temperature and humidity storage: Temperature: 30℃ /60℃/85℃, Relative humidity : 60%RH/85%RH Reflowsimulate: Test only convection	Temperaturebox size (L × W × H): 950mm X800mmX1440mm; Temperature and humidity storage size (L × W × H): 1000mm ×1000mm×1000mm Reflow size (L × W × H): 500mm×400mm×50mm	

					reflow welding; Peak temperature: 300°C		
				《Moisture/Reflow Sensitivity Classification for Non-hermetic Surface Mount Devices (SMDs)》 J-STD-020F-2022 Clause5	Test only: Temperaturestorage: Temperature: 125°C Temperature and humidity storage: Temperature: 30°C /60°C/85°C, Relative humidity : 60%RH/85%RH Reflowsimulate: Test only convection reflow welding; Peak temperature: 300°C	Temperaturebox size (L × W × H): 950mmX800mmX1440mm; Temperature and humidity storage size (L × W × H): 1000mm ×1000mm×1000mm Reflow size (L × W × H): 500mm×400mm×50mm	
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J	Test only: Temperaturestorage: Temperature: 125°C Temperature and humidity storage: Temperature: 30°C /60°C/85°C, Relative humidity : 60%RH/85%RH Reflowsimulate: Test only convection reflow welding; Peak temperature: 300°C	Temperaturebox size (L × W × H): 950mmX800mmX1440mm; Temperature and humidity storage size (L × W × H): 1000mm ×1000mm×1000mm Reflow size (L × W × H): 500mm×400mm×50mm	
				《Failure Mechanism Based Stress Test Qualification For Discrete Semiconductors》 AEC-Q101-RCV-E	Test only: Temperaturestorage: Temperature: 125°C Temperature and humidity storage: Temperature: 30°C /60°C/85°C, Relative humidity : 60%RH/85%RH Reflowsimulate: Test only convection reflow welding; Peak	Temperaturebox size (L × W × H): 950mmX800mmX1440mm; Temperature and humidity storage size (L × W × H): 1000mm ×1000mm×1000mm Reflow size (L × W × H): 500mm×400mm×50mm	

					temperature: 300°C	
		2	Temperature and humidity bias test	《Steady-State Temperature-Humidity Bias Life Test》 JESD22-A101D.01-2021 Clause4	Test only: Temperature: 85°C, Relative humidity: 85%RH	Inner box size (L × W × H): 1000mm×1000mm ×1000mm
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J	Test only: Temperature: 85°C, Relative humidity: 85%RH	Inner box size (L × W × H): 1000mm×1000mm ×1000mm
		3	High temperature bias test	《Temperature, Bias, and Operating Life》 JESD22-A108G-2022 Clause4	Test only: Temperature: 25°C~ 175°C	Temperature box size (L × W × H): 950mmX800mmX1440mm
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J	Test only: Temperature: 25°C~ 175°C	Temperature box size (L × W × H): 950mmX800mmX1440mm
		4	High temperature storage test	《High Temperature Storage Life》 JESD22-A103E.01-2021 Clause4	Test only: Temperature: 125°C~ 200°C	Temperature box size (L × W × H): 950mmX800mmX1440mm
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J	Test only: Temperature: 125°C~ 200°C	Temperature box size (L × W × H): 950mmX800mmX1440mm
		5	High acceleration stress test	《Accelerated Moisture Resistance - Unbiased HAST》 JESD22-A118B.01-2021 Clause4	Test only: Temperature: 130°C /110°C, Relative humidity: 85%RH, pressure: 122kPa/230kPa	Inner box size(Diameter X depth): 340mmX475mm
				《Highly Accelerated Temperature and Humidity Stress Test (HAST)》 JESD22-A110E.01-2021 Clause4	Test only: Temperature: 130°C /110°C, Relative humidity: 85%RH, pressure: 122kPa/230kPa	Inner box size(Diameter X depth): 340mmX475mm
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J	Test only: Temperature: 130°C /110°C, Relative humidity: 85%RH, pressure: 122kPa/230kPa	Inner box size(Diameter X depth): 340mmX475mm

				《Failure Mechanism Based Stress Test Qualification For Discrete Semiconductors》 AEC-Q101-RCV-E	Test only: Temperature: 130°C /110°C, Relative humidity: 85%RH, pressure: 122kPa/230kPa	Inner box size(Diameter X depth): 340mmX475mm	
		6	Autoclave test	《Accelerated Moisture Resistance - Unbiased Autoclave 》 JESD22-A102E-2015 Clause4	Test only: Temperature: 121°C, Relative humidity: 100%RH	Inner box size(Diameter X depth): 340mmX475mm	
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J	Test only: Temperature: 121°C, Relative humidity: 100%RH	Inner box size(Diameter X depth): 340mmX475mm	
				《Failure Mechanism Based Stress Test Qualification For Discrete Semiconductors》 AEC-Q101-RCV-E	Test only: Temperature: 121°C, Relative humidity: 100%RH	Inner box size(Diameter X depth): 340mmX475mm	
		7	Temperature cycle test	《Temperature Cycling》 JESD22-A104F.01-2023 Clause4, 条件 B,C	Test only: Temperature: -65°C ~150°C	Inner box size (L × W × H): 400mm×500mm×400mm。Contingency: Connecting piece。	
				《Failure Mechanism Based Stress Test Qualification For Integrated Circuits》 AEC-Q100-REV-J	Test only: Temperature: -65°C ~150°C	Inner box size (L × W × H): 400mm×500mm×400mm。Contingency: Connecting piece。	No test Grade 0
				《Failure Mechanism Based Stress Test Qualification For Discrete Semiconductors》 AEC-Q101-RCV-E	Test only: Temperature: -65°C ~150°C	Inner box size (L × W × H): 400mm×500mm×400mm。Contingency: Connecting piece。	